

Docket No. 241072US2SRD/hc



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Naoki SHUTOH, et al.

SERIAL NO: 10/629,624

GAU:

FILED: July 30, 2003

EXAMINER:

FOR: THERMOELECTRIC MATERIAL AND THERMOELECTRIC ELEMENT

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

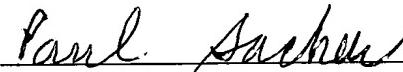
- Each item of information contained in this information disclosure statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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STATEMENT OF RELEVANCY

Reference AO (JP 2001-189495) on Form 1449:

This reference relates the crystal structure is similar to our invention.

Reference AW on Form 1449:

This reference relates to doping ZrNiSn-based thermoelectric materials. But there is no description of (Zr, Hf, Ti) NiSn compound that we invent.

Reference AX on Form 1449:

This reference relates to p-type half-Heusler materials. But there is no description of MNiSb compound that we invent.

OCT 28 2003

SHEET 1 OF 1

Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 241072US2SRD	SERIAL NO. 10/629,624		
LIST OF REFERENCES CITED BY APPLICANT		APPLICANT Naoki SHUTOH, et al.					
		FILING DATE July 30, 2003		GROUP			
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION		
					YES	NO	
	AO	2001-189495	07/10/2001	JAPAN			X
	AP						
	AQ						
	AR						
	AS						
	AT						
	AU						
	AV						
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
AW	H. HOHL, et al., J. Phys.: Condens., matter 11, pages 1697-1709, "EFFICIENT DOPANTS FOR ZrNiSn-BASED THERMOELECTRIC MATERIALS", 1999						
AX	K. MASTRONARDI, et al., Applied Physics Letters, vol. 74, no. 10, pages 1415-1417, "ANTIMONIDES WITH THE HALF-HEUSLER STRUCTURE: NEW THERMOELECTRIC MATERIALS", March 8, 1999						
AY							
AZ					<input type="checkbox"/> Additional References sheet(s) attached		
Examiner					Date Considered		

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



LIST OF RELATED CASES

<u>Docket Number</u>	<u>Serial or Patent Number</u>	<u>Filing or Issue Date</u>	<u>Inventor/Applicant</u>
221292US2 SRD	10/105,341	03/26/02	SHUTOH et al.
241072US2 SRD*	10/629,624	07/30/03	SHUTOH et al.

*Present Application; listed for information
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